



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	31-10-2022
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Material Declaration champion	Representative Title	Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32L4P5AGI6 STM32L4P5AGI6TR	200Q*471XXXZ	A	9991	31-10-2022
	Amount	UoM	Unit type	ST ECOPACK Grade
	64.68	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	NAC	Copper Alloy	96.5SN/3.5AG_0.20MM	

Package Designator	Size	Nbr of instances	Shape	
BGA	7x7	169	bulk solder	
Comment	Package : A0YV UFBGA 7X7X0.6 169L P 0.5 MM 8502430			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	200Q*471XXXZ				5999999.0	1000014.6
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	3.518	mg	supplier	die	Silicon (Si)	7440-21-3		2.837	mg	806424	43862
				supplier	metallization	Aluminium (Al)	7429-90-5		0.033	mg	9380	510
				supplier	metallization	Copper (Cu)	7440-50-8		0.289	mg	82149	4468
				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	284	15
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.093	mg	26435	1438
				supplier	metallization	Titanium (Ti)	7440-32-6		0.003	mg	853	46
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	569	31
				supplier	Passivation	Silicon Nitride	12033-89-6		0.073	mg	20750	1129
				supplier	Passivation	Silicon Oxide	7631-86-9		0.187	mg	53155	2891
Substrate_A268290	M-011 Other inorganic materials	19.466	mg	supplier	BT-substrate	Thermosetting resin (Inorganic filler)	Undisclosed		1.557	mg	80000	24077
					BT-substrate	Glass cloth	65997-17-3		7.592	mg	390000	117374
					BT-substrate	Copper foil	7440-50-8		7.981	mg	410000	123393
					Solder mask	2-benzyl-2-dimethylamino-4-morpholinobutyr	119313-12-1		0.779	mg	40000	12038
					Solder mask	Propanol, 1(or 2)-(2-methoxymethylethoxy)-	34590-94-8		0.642	mg	33000	9932
					Solder mask	Solvent naphtha (petroleum), heavy arom.	64742-94-6		0.905	mg	46500	13995
					Solder mask	Copper,[29H,31H-phthalocyaninato(2-)-]kappa	147-14-8		0.010	mg	500	150
					film	Butadiene, acrylonitrile polymer, carboxy-term	68610-41-3		3.517	mg	686250	54376
					film	Formaldehyde, polymer with (chloromethyl)ox	37382-79-9		1.505	mg	293750	23276
DA ATB-125-12	M-011 Other inorganic materials	5.125	mg	supplier	film	[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	2530-83-8		0.051	mg	10000	792
					film	Reaction product: bisphenol-A-(epichlorhydrin)	25068-38-6		0.051	mg	10000	792
					Bonding wire	Copper	7440-50-8		0.540	mg	965500	8344
					Bonding wire	Palladium	7440-05-3		0.017	mg	31000	268
					Bonding wire	Gold	7440-57-5		0.002	mg	3500	30
					Molding Compound	Epoxy resin	Trade secret		1.276	mg	40000	19730
					Molding Compound	Silica(Fused)	60676-86-0,7631-86-9		28.713	mg	900000	443919
					Molding Compound	Phenol resin	Trade secret		1.787	mg	56000	27622
					Molding Compound	Carbon Black	1333-86-4		0.128	mg	4000	1973
Solder balls (96.55N/3.5AG_0.20MM)	Solder	4.110	mg	supplier	Solder	Tin (Sn)	7440-31-5		3.966	mg	965000	61320
					Solder	Silver (Ag)	7440-22-4		0.144	mg	35000	2224